

# Can Embedded Applications Utilize the Latest Flash Storage Technologies?

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- Storage Tech Headlines!
- Embedded Applications Value set
- Flash Storage Technology Review
  - a) Industry Standards
  - b) Form-factors
  - c) SSD Feature Set
  - d) Media
- Back to the Question?
- Food For Thought...



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- Feb. SanDisk Fusion ioMemory SSD announcement 3.2TB SSD \$17,870.00!!
- Feb. Shannon Systems Direct-IO 6.4TB Enterprise SSD \$ Call
- Mar. Intel 2.5" NVMe SSD 480GB Random R/W 480K/170K IOPS
- Mar. Samsung Introduces World's Largest SSD 15.36TB!! (inc. free shipping!)
- Mar. Seagate & Micron Enterprise 12Gbps SAS SSD 3.2TB, 10 DWPD
- Mar Intel Announces New 3D NAND And Dual-Port NVMe SSDs 2TB, 32 Layer 3D NAND
- Mar. Intel SATA 6Gbps, 1TB TLC SSD 0.1 DWPD "Read Centric"
- Apr. Toshiba PCIe Gen 3 NVMe 1.0 2.5" Enterprise SSD 4TB, Random R/W 660K/ 185K IOPS
- Apr. SK Hynix Enterprise M.2 SSD 36 Layer 3D NAND, NVMe 1.2, 1.3 DWPD
- May Seagate Nytro XP6500 Enterprise SSD Flash Accelerator Random R/W 300K/100K IOPS

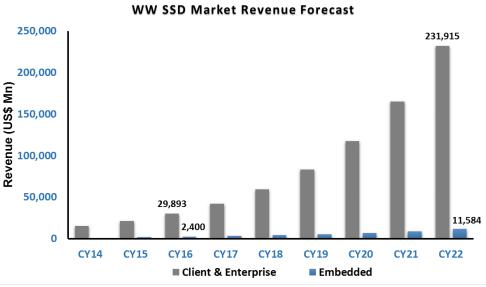


#### **<u>Client & Enterprise:</u>**

- C&E has and will always dominate the WW SSD market, CAGR >40% thru CY22
- CY14 Client dominated the C&E Revenue, but Enterprise SSD has a greater YoY growth share

#### **Embedded:**

- Embedded estimated to be a \$2B WW market, <u>assuming</u> a CAGR of 20% = \$11.5B CY22
- Smaller market, supported by a large array of technologies & solutions sets
- Trend is toward leveraging solutions driven by C&E market, less customization, a little more compromise, but....



Source: TMR Analysis (August 2015)



# Memory Top 5 Storage Selection Criteria

#### **Consumer/Client**

# **Embedded**

Cost Cost Cost Performance Capacity Reliability Endurance Lifecycle Cost Power

#### **Enterprise**

Performance Capacity Power Cost Reliability

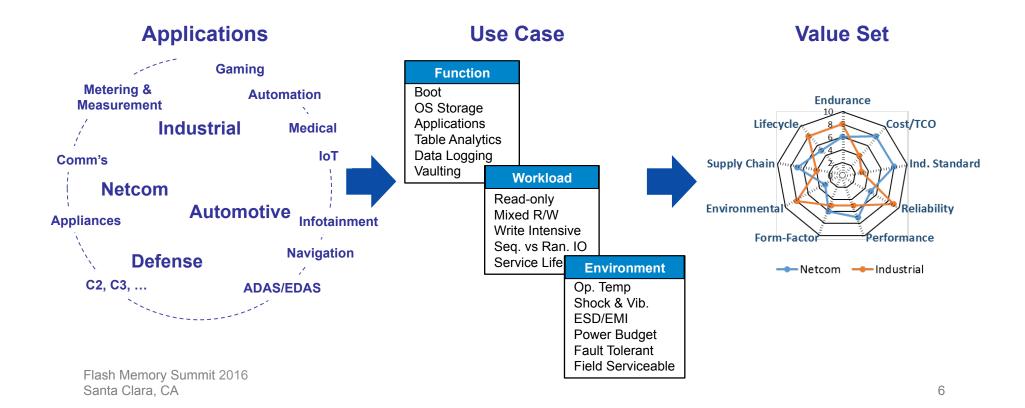
#### Embedded Applications, typically (but not always) value

Reliability & Endurance over Performance

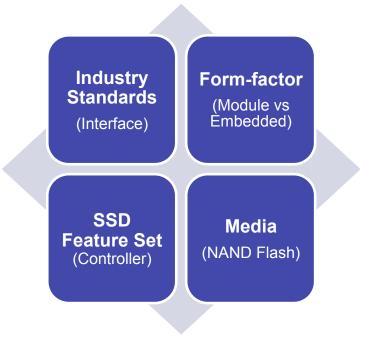
Product Lifecycle over Leading Edge Technologies

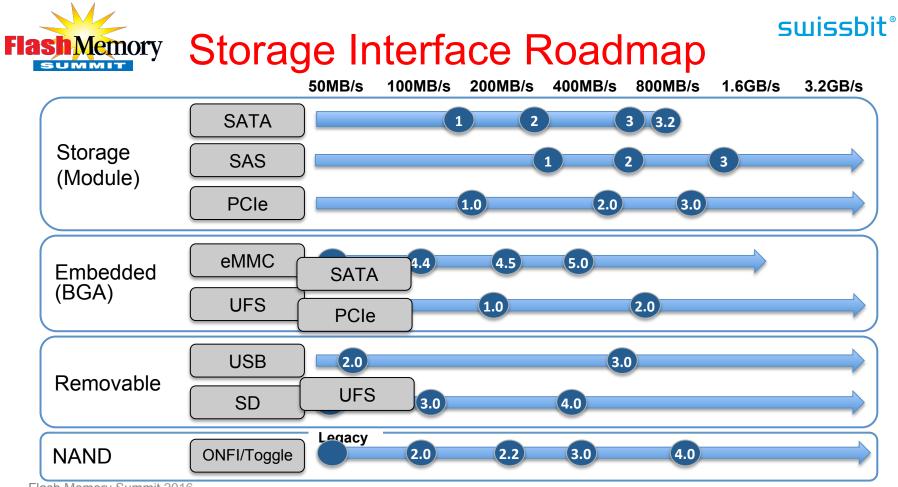
Quality/Service/Support (TCO) over Lowest "Initial" Cost





# Flash Memory Flash Storage Technology Review





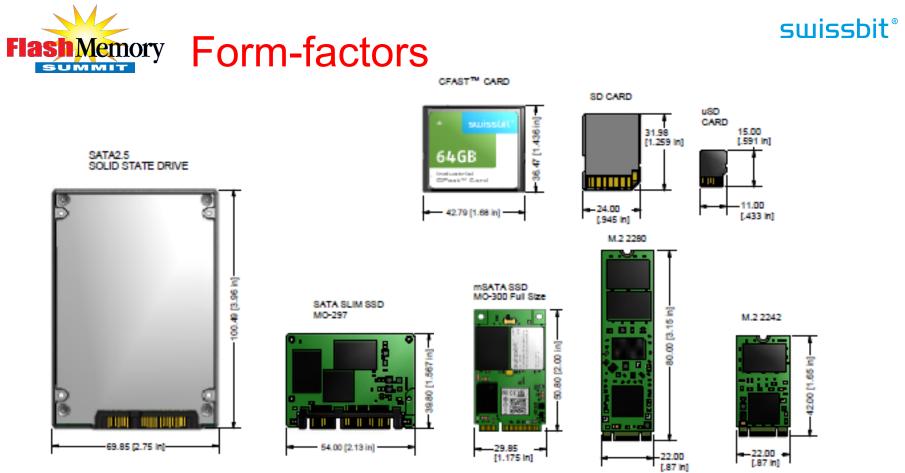
Original Source: Flash Memory Summit 2012



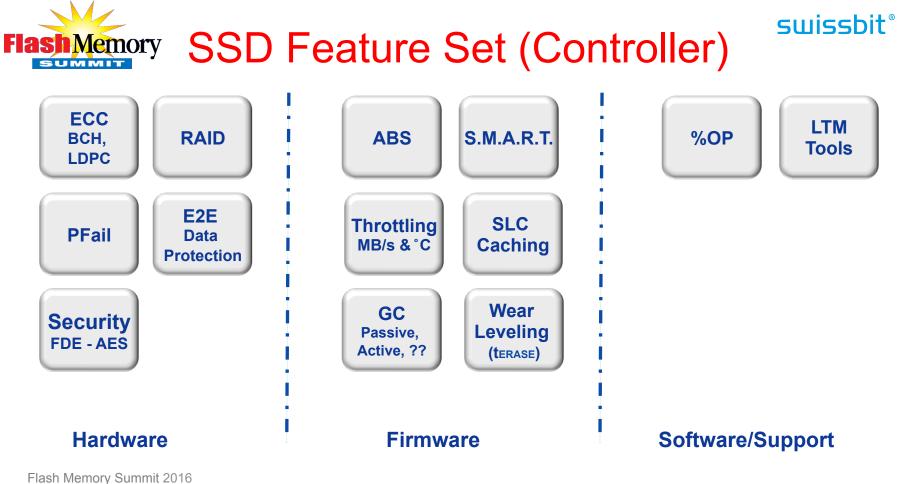
# Industry Standards (Interface)

Standard Strengths & Weaknesses	Embedded Adoption	
	Netcom	Industrial
+ Interface is pervasive & mature - 8b/10b encoding	$\checkmark\checkmark$	~
+ CMD Queue Depth: 32 + Reliable Write Mode - Performance Limited	$\checkmark$	$\checkmark$
+ Serial Attached SCSI - Many Chips sets lack dual port support	? 🗴	? 🗴
+ Interface is pervasive & mature - Power Consumption	$\checkmark$	$\checkmark$
+ Bi-directional R/W + No Protocol Trans. Layer - Power Consumption	$\checkmark$	?
	<ul> <li>+ Interface is pervasive &amp; mature</li> <li>- 8b/10b encoding</li> <li>+ CMD Queue Depth: 32</li> <li>+ Reliable Write Mode</li> <li>- Performance Limited</li> <li>+ Serial Attached SCSI</li> <li>- Many Chips sets lack dual port support</li> <li>+ Interface is pervasive &amp; mature</li> <li>- Power Consumption</li> <li>+ Bi-directional R/W</li> <li>+ No Protocol Trans. Layer</li> </ul>	Strengths & WeaknessesNetcom+ Interface is pervasive & mature - 8b/10b encodingImage: Comparison of the system of the system - 8b/10b encoding+ CMD Queue Depth: 32 + Reliable Write Mode - Performance LimitedImage: Comparison of the system of the system of the system ort support+ Serial Attached SCSI - Many Chips sets lack dual port support? *+ Interface is pervasive & mature - Power ConsumptionImage: Comparison of the system of the system 

Flash Memory Summit 2016 Santa Clara, CA swissbit®



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- 2D Planar (SLC, pSLC, MLC) anticipate a decline in production and market tightening, as the semi's focus their attention on the emerging 3D NAND market demand
- 3D MLC is here, expect good traction for higher capacity embedded (Infrastructure) drives, but only after it is a proven solution for the target use cases
- 3D TLC will likely remain in the C&E space, Embedded customers don't need the capacity and will value the endurance over GB's
- NVM technologies (e.g., PCM, STT-MRAM, etc.) are coming but still "<u>years</u>" from being a real challenger to displace NAND

Flash Memory Summit 2016 Santa Clara, CA "Micron, Samsung in Flash Battle" EETimes, Feb. 2016





#### "Can Embedded Applications Utilize the Latest Flash Storage Technologies?"

- Yes! Embedded Storage Applications have and will continue to benefit from the Latest Storage Technology developments driven by the Client & Enterprise market.
- Expect the NetCom market will actively leverage the PCIe transport and NVMe protocol benefits in next generation platforms (currently in development).
- Traditional Embedded Industrial applications are more likely to rely "Tried and True" (e.g., SD, eMMC, SATA, etc.) versus "Fast and Furious" (e.g., PCIe NVMe)



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Given the Embedded Applications Value set...

Is it possible that the majority of Embedded customers stay the course, picking up incremental C&E Storage Technology improvements (e.g., SSD Feature Set, NAND, etc.),

...and hold out for the "Big Bang!" disruptive innovation of NVM working memory/storage (i.e., Shared Memory) solution sets in the CY20+ timeframe?



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